



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.300 MAX.

MULTIPLICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					24 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	S.T	K.M	SEP 29, 71
					SCALE 10/1	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION		DRAWING NO.	SHEET
					KYOTO JAPAN		KD-F90752	3/		